



US 20240213220A1

(19) **United States**

(12) **Patent Application Publication**
HUH et al.

(10) **Pub. No.: US 2024/0213220 A1**

(43) **Pub. Date: Jun. 27, 2024**

(54) **METHOD, APPARATUS, AND SYSTEM WITH INTEGRATED CIRCUIT MANUFACTURING**

(52) **U.S. Cl.**

CPC **H01L 25/0657** (2013.01); **H01L 24/08** (2013.01); **H01L 25/50** (2013.01); **H01L 2224/08146** (2013.01); **H01L 2225/06548** (2013.01); **H01L 2924/19011** (2013.01); **H01L 2924/19041** (2013.01); **H01L 2924/19042** (2013.01)

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(57)

ABSTRACT

(21) Appl. No.: **18/328,848**

(22) Filed: **Jun. 5, 2023**

(30) **Foreign Application Priority Data**

Dec. 23, 2022 (KR) 10-2022-0182826

Publication Classification

(51) **Int. Cl.**

H01L 25/065 (2006.01)

H01L 23/00 (2006.01)

H01L 25/00 (2006.01)

An integrated circuit (IC) system including a first substrate comprising passive components, a first power managing IC chip including a first power managing IC stacked on the first substrate, first IC chip group including a IC stacked on top of the first power managing IC chip, a control IC chip, stacked on top of the first IC group, including a control IC configured to control the first IC and a second IC of a second IC chip group, the second IC chip group including the second IC stacked on top of the control IC chip, a second power managing IC chip including a second power managing IC stacked on top of the second IC chip group, and a second substrate comprising passive components stacked on top of the second power managing IC chip.

